UNIVERSITÄT SIEGEN

SPI 2022

26th IEEE Workshop On Signal And Power Integrity

May 22-25, 2022 - Siegen, Germany

www.spi-conference.org ✉ spi@uni-siegen.de

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Important Dates

Full Paper Submission: Jan 31st, 2022

Notification of Acceptance: Mar 31th, 2022

Call for Papers

26th IEEE Workshop On Signal And Power Integrity
May 22-25, 2022

Over the past two decades, the IEEE Workshop on Signal and Power Integrity (SPI) has evolved into a forum of exchange on the latest research and developments on design, characterization, modeling, simulation and testing for Signal and Power Integrity at chip, package, board and system level. The workshop brings together developers and researchers from industry and academia in order to encourage cooperation.

The Committee is looking forward to the 26th Edition which will take place in Siegen Germany. The SPI 2022 technical program will include both oral and poster sessions. A number of prominent experts will be giving tutorials on areas of emerging interest. Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements.

Topics

- Modeling and simulation for SI/PI
- Coupled signal and power Integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-on-chip
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects
- AI in electronics design